Data sheet Product ICK BGA 11 x 11 x 10



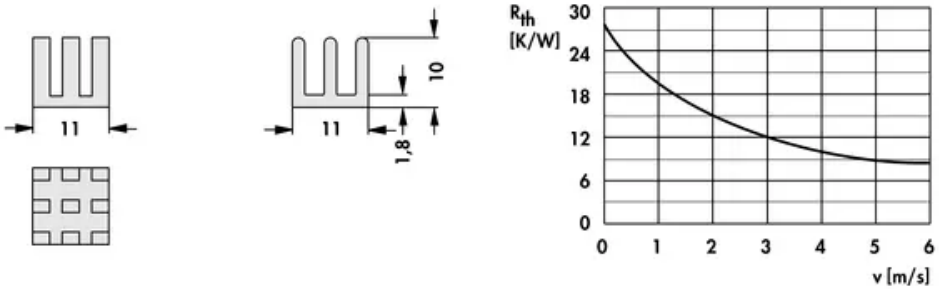
Heatsinks and active heatsinks for processors>Heatsinks for BGAs

11 x 11 x 10 mm, for IC design BGA and others

Features

way of fixation:	• **therm. conductive foil** • **therm. cond. adhesive**
socket:	**universal**
suitable for processor type:	**universal**
width:	**11 mm**
height:	**10 mm**
plate thickness:	**1.8 mm**
length:	**11 mm**
thermal resistance:	**27.5 - 8.1 K/W**
dissipation loss:	**2.2 W**
surface:	**black anodised**

Technical Drawing



Fischer Elektronik GmbH & Co. KG
DEUTSCHLAND • GERMANY • ALLEMAGNE
Nottebohmstraße 28
58511 Lüdenscheid
Telefon +49 2351 435-0
Telefax +49 2351 45754
info@fischerelektronik.de
www.fischerelektronik.de